

Title (en)
SULFONAMIDE BASED POLYMERS FOR COPPER ELECTROPLATING

Title (de)
SULFONAMIDBASIERTE POLYMERE ZUR KUPFERGALVANISIERUNG

Title (fr)
POLYMÈRES À BASE DE SULFONAMIDE POUR ÉLECTRODÉPOSITION DE CUIVRE

Publication
EP 3048190 B1 20180627 (EN)

Application
EP 15194687 A 20151116

Priority
US 201414585227 A 20141230

Abstract (en)
[origin: EP3048190A1] Sulfonamide based polymers are reaction products of sulfonamides and epoxides. The polymers may be used as levelers in copper electroplating baths, to provide good throwing power. Such reaction products may plate copper or copper alloys with good surface properties and good physical reliability.

IPC 8 full level
C25D 3/38 (2006.01); **C25D 3/58** (2006.01); **H05K 3/18** (2006.01); **H05K 3/24** (2006.01); **H05K 3/42** (2006.01); **C25D 3/60** (2006.01)

CPC (source: CN EP US)
C07C 303/40 (2013.01 - CN); **C07C 311/17** (2013.01 - CN); **C07D 233/60** (2013.01 - CN); **C07D 301/00** (2013.01 - CN);
C07D 303/20 (2013.01 - CN); **C25D 3/38** (2013.01 - CN EP US); **C25D 3/58** (2013.01 - EP US); **C25D 5/38** (2013.01 - EP US);
H05K 3/188 (2013.01 - EP US); **H05K 3/241** (2013.01 - EP US); **H05K 3/423** (2013.01 - EP US); **C25D 3/60** (2013.01 - EP)

Cited by
WO2018073011A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3048190 A1 20160727; EP 3048190 B1 20180627; CN 105732542 A 20160706; CN 105732542 B 20200214; JP 2016148025 A 20160818;
JP 6294291 B2 20180314; KR 101797509 B1 20171115; KR 20160081803 A 20160708; TW 201623359 A 20160701; TW I574986 B 20170321;
US 2016186345 A1 20160630; US 2016186349 A1 20160630; US 9562300 B2 20170207; US 9611560 B2 20170404

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EP 15194687 A 20151116; CN 201510959371 A 20151218; JP 2015241159 A 20151210; KR 20150182920 A 20151221;
TW 104140992 A 20151207; US 201414585227 A 20141230; US 201514980562 A 20151228